Fast Amp PCB Manufacturing Instructions

University of Pennsylvania, Dept. of Physics and Astronomy

BOARD NAME: FAST AMP

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MANUFACTURING NOTES

1. This is a 4 layer board with the following order:

TOP

GND

POWER

BOTTOM

1. MATERIAL: FR4
2. BOARD THICKNESS: 62 mils
3. COPPER THICKNESS: all layers 1oz copper.
4. All holes plated through unless otherwise noted.
5. FINISH: immersion gold